

ON Semiconductor			10/15/2019	
Base Part		FDS8876	HF	Pb-free
Orderable Part		FDS8876	Total weight (mg)	85.792
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	2.78	Silicon (Si)	7440-21-3	100
Die Attach Epoxy	0.352	Silver (Ag)	7440-22-4	85
		Phenolic Resin-2	54208-63-8	15
Lead Frame	38.507	Zinc (Zn)	7440-66-6	0.12984652
		Iron (Fe)	7439-89-6	2.39956372
		Copper (Cu)	7440-50-8	97.42124808
		Phosphorus (P)	7723-14-0	0.04934168
Mold Compound-Black	43.1	Ortho Cresol Novolac Resin	29690-82-2	7
		Carbon Black (C)	1333-86-4	1
		Fused Silica (SiO2)	60676-86-0	90
		Phenolic Resin (Novolac)	9003-35-4	2
Plating	0.869	Palladium (Pd)	7440-05-3	8.0552359
		Nickel (Ni)	7440-02-0	89.98849252
		Gold (Au)	7440-57-5	1.95627158
Wire Bond - Cu	0.184	Copper (Cu)	7440-50-8	100
<p><b>Materials Disclosure Disclaimer:</b> Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p><a href="http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF">http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</a></p>				